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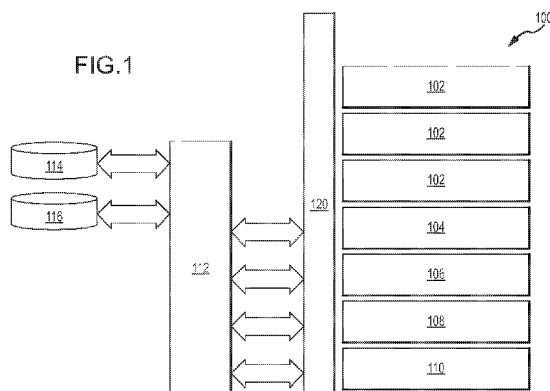
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(54) **Title:** ENHANCED RE-HOSTING CAPABILITY FOR LEGACY HARDWARE AND SOFTWARE



(57) **Abstract:** Embodiments of the invention are directed toward systems and methods that execute legacy semiconductor applications using a non-legacy controller. In some embodiments a hardware abstraction layer and/or an emulator can be used to provide communication between a non-legacy operating system and legacy components including legacy applications. In some embodiments various methods and/or devices can be used to emulate and/or translate communications between legacy and non-legacy components.